IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				Materials and	rials and Mfg Information			
upplier	r Information													
ompany	name*	Company un	Company unique ID			Unique ID Authority				Response Date*				
onsemi											2024-04-25			
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	Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Manufacturing	Manufacturing Site		UOM	Unit Type	
		FDA28N50F UF 500V 175n		UF 500V 175mOh	5mOhm F TO3PN		2024-04-25 CPA			5434.65	mg	Each		
lanufa	cturing Process Inform		Famminal Daga	Aller	STD-020 MS	I. Dating	Dools Decode	na Dody Tomor	ature Max Time	ot Dook Tomme	Number	er of Reflow Cy	olog	
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RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not independently verified information provided by others, supplier as a minimum, its applier by the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's St										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	41.8	mg	Supplier	Silicon (Si)	7440-21-3		41.8	mg
Die Attach	1.84	mg	Supplier	Silver (Ag)	7440-22-4		0.0276	mg
			A	Lead (Pb)	7439-92-1	7a	1.7204	mg
			Supplier	Tin (Sn)	7440-31-5		0.092	mg
Lead Frame	3624.71	mg	Supplier	Tin (Sn)	7440-31-5		3.62	mg
			Supplier	Copper (Cu)	7440-50-8		3620.0017	mg
			Supplier	Phosphorus (P)	7723-14-0		1.088	mg
Mold Compound-Black	1736.8	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		52.2001	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		347.9991	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		43.5001	mg
			Supplier	Carbon Black (C)	1333-86-4		13.1	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1280.0009	mg
Plating	26.5	mg	Supplier	Tin (Sn)	7440-31-5		26.5	mg
Wire Bond - Al	3.0	mg	Supplier	Aluminum (Al)	7429-90-5		3	mg